CLAIMS

What is claimed is:

1. A method, comprising:

a. providing a preform, the preform having:

i. a first bottom with a first diameter; and

ii. a first upward extending sidewall surrounding the first bottom and extending upward from the first bottom so as to form a fluid retaining interior region of the preform, the first sidewall terminating at a first rim and having a first height;

b. forming a first channel in the first bottom, the first channel having an opening in an external surface of the first bottom;

c. drawing the preform into the shape of a vessel, the vessel having:

i. a second bottom with a second diameter that is smaller than the first diameter;

ii. a second upward extending sidewall surrounding the second bottom and extending upward from the second bottom so as to form a fluid retaining interior region of the vessel, the second sidewall terminating at a second rim and having a second height that is greater than the first height; and

iii. a second channel extending through a portion of the second bottom and further extending upward into and through a portion of the second sidewall, the second channel having an opening positioned in an external surface of the second sidewall;

d. positioning a thermal sensor within the second channel so that a thermal sensing device of the thermal sensor is positioned within the portion of the second bottom, and further so that one or more sensor leads of the thermal sensor extend from the portion of the second bottom upward into and through the portion of the second sidewall, and further so that the one or more sensor leads extend out of the opening in the external surface of the second sidewall;

e. routing the one or more sensor leads within a flange of a handle;

f. coupling the flange of the handle to the vessel, wherein the flange is coupled to the vessel in a position over the opening in the external surface of the second sidewall, wherein an electronic circuit is positioned on or in the handle; and

g. coupling the one or more sensor leads to the electronic circuit.

2. A method, comprising:

a. providing a preform, the preform having:

i. a first bottom with a first diameter;

ii. a first upward extending sidewall surrounding the first bottom and extending upward from the first bottom so as to form a fluid retaining interior region of the preform, the first sidewall terminating at a first rim and having a first height; and

iii. a first channel formed in the first bottom and having an opening in an external surface of the first bottom;

b. changing the preform into the shape of a vessel, the vessel having:

i. a second bottom with a second diameter that is smaller than the first diameter;

ii. a second upward extending sidewall surrounding the second bottom and extending upward from the second bottom so as to form a fluid retaining interior region of the vessel, the second sidewall terminating at a second rim and having second height that is greater than the first height; and

iii. a second channel extending through a portion of the second bottom and further extending upward into and through a portion of the second sidewall, the second channel having an opening positioned in an external surface of the second sidewall; and

c. positioning a thermal sensor within the second channel, the thermal sensor extending through the portion of the second bottom and further extending upward into and through the portion of the second sidewall.

3. The method of Claim 2, further comprising forming the first channel in the first bottom of the preform.

4. The method of Claim 2, further comprising forming the preform from a disk.

5. The method of Claim 2, wherein changing the preform into the shape of the vessel comprises drawing the preform into the shape of the vessel.

6. The method of Claim 2, further comprising:
    a. coupling a handle to the vessel, the handle having an electronic circuit positioned on or in the handle; and
    b. coupling a portion of the thermal sensor to the electronic circuit.

7. The method of Claim 6, wherein coupling the handle to the vessel comprises coupling a flange of the handle to the vessel, wherein the flange is coupled to the vessel in a position over the opening in the external surface of the second sidewall.

8. The method of Claim 2, wherein the thermal sensor comprises:
    a. a thermal sensing device; and
    b. one or more sensor leads communicatively coupled to the thermal sensing device.

9. The method of Claim 8, further comprising:
    a. coupling a handle to the vessel, the handle having an electronic circuit positioned on or in the handle; and
    b. coupling the one or more sensor leads to the electronic circuit.

10. The method of Claim 2, wherein the vessel is a pot, a pan, a skillet, a sauté pan, a stock pot, or a chef's pan.